

ABSTRACT OF THE DISCLOSURE

A DCA memory module. The memory module has a substrate, at least a chip set and a molding compound. The chip set is adhered on the substrate and is electrically connected to the substrate. The chip set has a plurality of chips formed side by side as one group, and each chip is electrically connected to each other by a plurality of circuits. The molding compound encapsulates at least a portion of the electrical connection between the chip set and the substrate.

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